

Effect of deposition temperature on the crystallinity and polarization of Ga-doped HfO₂ films by atomic layer deposition.

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Ferroelectric random access memory (FRAM) is considered as one of next generation memory devices due to its merits such as low power consumption and fast operation speed.[1] Recently, HfO₂ thin films with non-centrosymmetric orthorhombic phase of the space group of P_{ca}2₁ attracted intensive attention because of their ferroelectric property. Also, effects of doping, stress, and substrate were studied to enhance the ferroelectricity of HfO₂ films.[2] It was reported that the ferroelectric behavior of HfO₂ was affected by conditions such as deposition and post annealing temperatures in addition to alloying elements.[2]

In this study, Ga-doped HfO₂ (Ga-HfO₂) films were deposited at various temperatures, ranging from 300 °C to 340 °C. Ga-HfO₂ films were grown on bottom electrodes of TiN by atomic layer deposition with Tetrakis(ethylmethylamino)-hafnium (TEMA-Hf), Trimethyl-gallium (TMG) as precursors and ozone as the oxidant. Then, top electrodes of 15nm-thick TiN were deposited by sputtering. And the post annealing was conducted by rapid thermal annealing (RTA) in N₂ atmosphere at 600 °C during 20s.

Chemical composition and bonding of Ga-HfO₂ films were investigated by X-ray photoelectron spectroscopy (XPS). Structural properties were examined by Grazing Incidence X-ray diffraction (GI-XRD). The ferroelectric behaviors of Ga-HfO₂ films were measured by P-V, PUND methods with electric pulses of 3.3 MV/cm at 50 kHz and the endurance of ferroelectric switching, in addition.

Ga concentration and the non-lattice oxygen in Ga-HfO₂ film were estimated to be 5.9 % and 17.2 %, respectively. GI-XRD shows an increased intensity in nano-crystalline peak with increasing deposition temperature. But the remanent polarization of Ga-HfO₂ film was decreased with increasing deposition temperature.

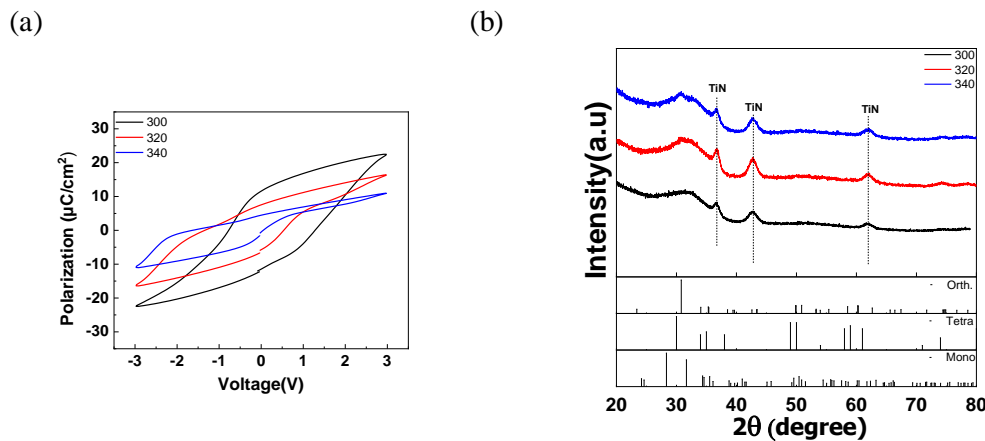


Fig 1. (a) P-V measurement (b) As grown Ga-HfO₂ GI-XRD spectra

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References

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